

Appln No. 10/090,915

Amdt date February 12, 2004

Reply to Office action of August 14, 2003

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A free-standing etching solution for the wet chemical pyramidal texture etching of silicon surfaces comprising: water, an alkaline reagent, isopropanol and ~~[an]~~ aqueous alkaline ethylene glycol ~~[solution]~~.

2. (Original) The free-standing etching solution as in claim 1, wherein the etching solution further comprises silicate.

3. (Original) The free-standing etching solution as in claim 1, wherein the etching solution contains 0.5 to 5 vol.% isopropanol.

4. (Original) The free-standing etching solution as in claim 1, wherein the proportion of isopropanol present in the etching solution is greater than the proportion of ethylene glycol.

5. (Currently Amended) The free-standing etching solution as in claim 4, wherein the ratio of isopropanol ~~[the]~~ to ethylene glycol is at maximum 1:1.

6. (Currently Amended) The free-standing etching solution as in claim 1, wherein the aqueous alkaline ethylene glycol ~~[solution]~~ is reacted with oxygen.

7. (Currently Amended) A free-standing etching solution for the wet chemical pyramidal texture etching of silicon

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surfaces comprising: water, sodium or potassium hydroxide, isopropanol and ~~[an]~~ aqueous alkaline ethylene glycol ~~[solution]~~.

8. (Original) The free-standing etching solution as in claim 1, further comprising silicate.

9. (Original) The free-standing etching solution as in claim 7, wherein the etching solution contains 0.5 to 5 vol.% isopropanol.

10. (Original) The free-standing etching solution as in claim 7, wherein the proportion of isopropanol present in the etching solution is greater than the proportion of ethylene glycol.

11. (Original) The free-standing etching solution as in claim 10, wherein the ratio of isopropanol to ethylene glycol is at maximum 1:1.

12. (Currently Amended) The free-standing etching solution as in claim 7, wherein the aqueous alkaline ethylene glycol ~~[solution]~~ is reacted with oxygen.